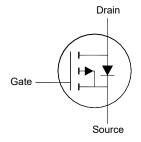
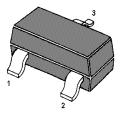
P-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- Surface-mounted package
- Halogen and Antimony Free(HAF), RoHS compliant





 Gate 2. Source 3. Drain SOT-23 Plastic Package

Applications

- Portable appliances
- Battery management

Absolute Maximum Ratings(at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	-V _{DS}	30	V
Gate-Source Voltage	V _{GS}	± 20	V
Continuous Drain Current	-I _D	3.5	А
Pulsed Drain Current 1)	-I _{DM}	14	Α
Total Power Dissipation 2)	P _{tot}	0.6 1.39	W
Operating Junction and Storage Temperature R	T _j , T _{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient ²⁾	Steady State t ≤ 10 s	Reja	208 90	°C/W

 $^{^{1)}}$ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.



²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate

MKA03P110LS-AH

Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit			
STATIC PARAMETERS								
Drain-Source Breakdown Voltage at -I _D = 250 μA	-V _{(BR)DSS}	30	-	-	V			
Zero Gate Voltage Drain Current at -V _{DS} = 24 V	-I _{DSS}	-	-	1	μΑ			
Gate-Source Leakage at V _{GS} = ± 20 V	I _{GSS}	-	-	± 100	nA			
Gate-Source Threshold Voltage at V _{DS} = V _{GS} , -I _D = 250 μA	-V _{GS(th)}	1	-	2.5	V			
Drain-Source On-State Resistance at -V _{GS} = 10 V, -I _D = 3.5 A at -V _{GS} = 4.5 V, -I _D = 2.5 A	R _{DS(on)}	- -	- -	72 110	mΩ			
DYNAMIC PARAMETERS	<u>, , , , , , , , , , , , , , , , , , , </u>		i	i	i			
Forward Transconductance at -V _{DS} = 10 V, -I _D = 2 A	g fs	-	3	-	S			
Gate resistance at $V_{DS} = 0 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Rg	-	6	-	Ω			
Input Capacitance at $-V_{DS} = 20 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _{iss}	-	410	-	pF			
Output Capacitance at $-V_{DS} = 20 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Coss	-	47	-	pF			
Reverse Transfer Capacitance at $-V_{DS} = 20 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _{rss}	-	40	-	pF			
Total Gate Charge at -V _{DS} = 20 V, -I _D = 3 A, -V _{GS} = 10 V at -V _{DS} = 20 V, -I _D = 3 A, -V _{GS} = 4.5 V	Qg	- -	8.3 4	- -	nC			
Gate to Source Charge at $-V_{DS} = 20 \text{ V}$, $-I_D = 3 \text{ A}$, $-V_{GS} = 10 \text{ V}$	Q _{gs}	-	1.8	-	nC			
Gate to Drain Charge at $-V_{DS} = 20 \text{ V}$, $-I_D = 3 \text{ A}$, $-V_{GS} = 10 \text{ V}$	Q_{gd}	-	1.5	-	nC			
Turn-On Delay Time at -V _{DD} = 20 V, -V _{GS} = 10 V, -I _D = 3 A, R _G = 3.3 Ω	t _{d(on)}	-	7.6	-	ns			
Turn-On Rise Time at -V _{DD} = 20 V, -V _{GS} = 10 V, -I _D = 3 A, R _G = 3.3 Ω	t _r	-	13	-	ns			
Turn-Off Delay Time at -V _{DD} = 20 V, -V _{GS} = 10 V, -I _D = 3 A, R _G = 3.3 Ω	$t_{\sf d(off)}$	-	9.6	-	ns			
Turn-Off Fall Time at -V _{DD} = 20 V, -V _{GS} = 10 V, -I _D = 3 A, R _G = 3.3 Ω	t _f	-	2.8	-	ns			
Body-Diode PARAMETERS								
Body Diode Voltage at -I _S = 1 A	-V _{SD}	-	-	1.2	V			
Body-Diode Continuous Current	-I _S	-	-	3.5	Α			
Body Diode Reverse Recovery Time at $-I_S = 3$ A, di/dt = 100 A / μ s	t _{rr}	-	9	-	ns			
Body Diode Reverse Recovery Charge at $-I_S = 3 \text{ A}$, di/dt = 100 A / μ s	Qrr	-	5	-	nC			



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

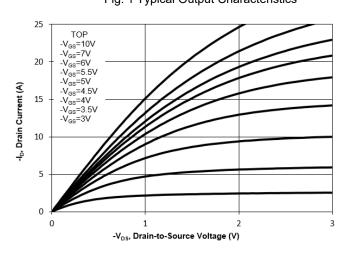


Fig. 2 Typical Transfer Characteristics

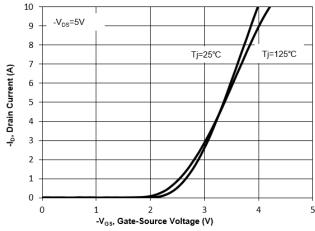


Fig. 3 on-Resistance vs. Drain Current

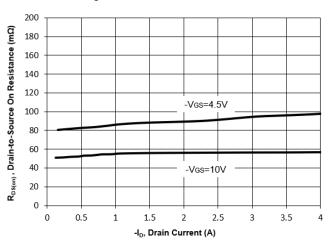


Fig. 4 On-Resistance vs. Gate-Source Voltage

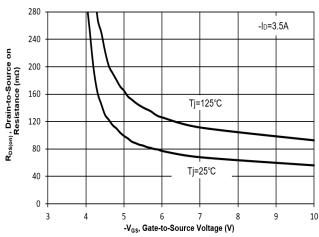


Fig. 5 on-Resistance vs.T_j

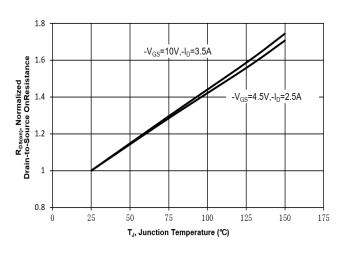
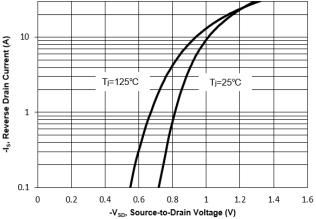


Fig. 6 Typical Forward Characteristics





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

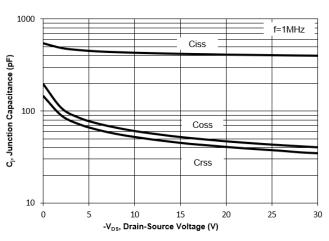


Fig. 8 Drain-Source Leakage Current vs. Tj

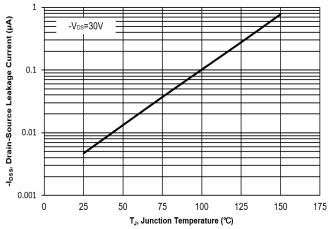


Fig. 9 V_{(BR)DSS} vs. Junction Temperature

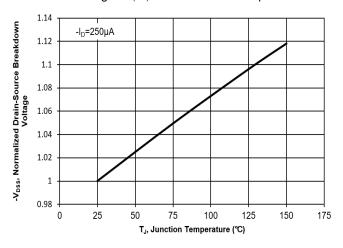


Fig. 10 Gate Threshold Variation vs. T_j

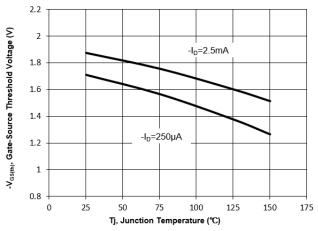
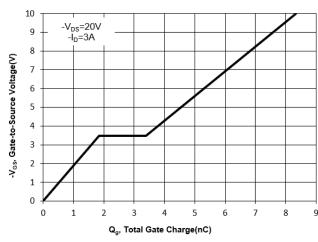


Fig. 11 Gate Charge





Test Circuits

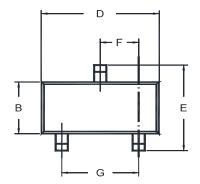
Fig.1-1 Switching times test circuit Fig.1-2 Switching Waveform RL Vds) Vgs 90% Rg 10% Vgs __ Vds Fig.2-1 Gate charge test circuit Fig.2-2 Gate charge waveform Qg Vgs Qgs Qgd

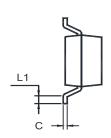


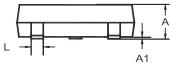
Charge

Package Outline (Dimensions in mm)

SOT-23

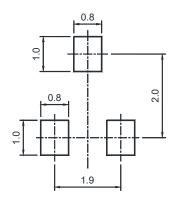






Unit	Α	A1	В	С	D	E	F	G	L	L1
	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
mm	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

Recommended Soldering Footprint



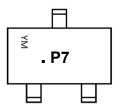
Packing information

Package	Tape Width	Pit	tch	Reel	Size		
	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000	

Marking information

- " P7 " = Part No.
- "•" = HAF (Halogen and Antimony Free)
- " YM " = Date Code Marking
- " Y " = Year
- " M " = Month

Font type: Arial



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